



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2023-04-08
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Material Declaration champion	<b>Representative Title</b>	Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H743IIT6	201T*450XXV	A	9991	2023-04-08
	Amount	UoM	Unit type	ST ECOPACK Grade
	1640.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	24x24	176	L bend	
Comment	Package : 1T LQFP 176 24x24x1.4 0110489			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	2017*450XXXV				6000000.0	1000000.0				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	16.499	mg	supplier	die	Silicon (Si)	7440-21-3		15.757	mg	955028	9608				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	5334	54				
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	16728	168				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	61	1				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	2727	27				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	485	5				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	61	1				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	19577	197				
				Leadframe (C7025 + Ag)	Copper & its alloys	425.000	mg		Leadframe	Copper (Cu)	7440-50-8		390.575	mg	919000	238155
									Leadframe	Nickel (Ni)	7440-02-0		13.175	mg	31000	8034
	Leadframe	Silicon (Si)	7440-21-3						5.100	mg	12000	3110				
	Leadframe	Magnesium (Mg)	7439-95-4						1.275	mg	3000	777				
	Leadframe	Silver (Ag)	7440-22-4						14.875	mg	35000	9070				
	Glue or tape	Silver (Ag)	7440-22-4						3.096	mg	755000	1888				
Glue epoxy (EN4900G)	Precious metals	4.100	mg		Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.103	mg	25000	63				
					Glue or tape	Bisphenol A Diacrylate	Proprietary		0.349	mg	85000	213				
					Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.226	mg	55000	138				
					Glue or tape	Butadiene copolymer	Proprietary		0.041	mg	10000	25				
					Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.226	mg	55000	138				
					Glue or tape	Peroxy Ketals	Proprietary		0.021	mg	5000	13				
					Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.021	mg	5000	13				
					Glue or tape	Methacrylate multialkoxy-substitutedalkyl ester	Proprietary		0.021	mg	5000	13				
				Bonding wire (Cu)	Precious metals	2.000	mg		Bonding wire	Copper (Cu)	7440-50-8		1.931	mg	965500	1177
									Bonding wire	Palladium (Pd)	7440-05-3		0.062	mg	31000	38
	Bonding wire	Gold (Au)	7440-57-5						0.007	mg	3500	4				
	Molding Compound	2,2'-(3,3',5,5'-Tetramethyl-1,1'-biphenyl)-4,4'	85954-11-6						47.060	mg	40000	28695				
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	1176.505	mg		Molding Compound	Epoxy resin	Proprietary		23.530	mg	20000	14348				
					Molding Compound	Phenol Resin	Proprietary		88.238	mg	75000	53804				
					Molding Compound	Silica(Amorphous) A	60676-86-0		834.730	mg	709500	508982				
					Molding Compound	Silica(Amorphous) B	7631-86-9		176.476	mg	150000	107607				
					Molding Compound	Carbon black	1333-86-4		6.471	mg	5500	3946				
					External Plating (Sn)	M-011 Other inorganic materials	15.895	mg	Matte Sn	Tin (Sn)	7440-31-5		15.893	mg	999900	9691
					Matte Sn	Impurities	-		0.002	mg	100	1				